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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.		
10/709,179	04/19/2004	Chih-Huang Chang	10544-US-PA	3178		
31561	7590	10/13/2005	<table border="1"> <tr> <td>EXAMINER</td> </tr> <tr> <td>HA, NATHAN W</td> </tr> </table>		EXAMINER	HA, NATHAN W
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HA, NATHAN W						
<b>JIANQ CHYUN INTELLECTUAL PROPERTY OFFICE</b> <b>7 FLOOR-1, NO. 100</b> <b>ROOSEVELT ROAD, SECTION 2</b> <b>TAIPEI, 100</b> <b>TAIWAN</b>			ART UNIT	PAPER NUMBER		
			2814			
DATE MAILED: 10/13/2005						

Please find below and/or attached an Office communication concerning this application or proceeding.

<b>Office Action Summary</b>	Application No.	Applicant(s)
	10/709,179	CHANG ET AL.
	Examiner	Art Unit
	Nathan W. Ha	2814

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

#### Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

#### Status

1) Responsive to communication(s) filed on 02 August 2005.

2a) This action is FINAL. 2b) This action is non-final.

3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

#### Disposition of Claims

4) Claim(s) 15-20 is/are pending in the application.

4a) Of the above claim(s) \_\_\_\_\_ is/are withdrawn from consideration.

5) Claim(s) \_\_\_\_\_ is/are allowed.

6) Claim(s) 15-20 is/are rejected.

7) Claim(s) \_\_\_\_\_ is/are objected to.

8) Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

#### Application Papers

9) The specification is objected to by the Examiner.

10) The drawing(s) filed on \_\_\_\_\_ is/are: a) accepted or b) objected to by the Examiner.  
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).  
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).

11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

#### Priority under 35 U.S.C. § 119

12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).

a) All b) Some \* c) None of:

1. Certified copies of the priority documents have been received.
2. Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

#### Attachment(s)

1) Notice of References Cited (PTO-892) 4) Interview Summary (PTO-413)  
2) Notice of Draftsperson's Patent Drawing Review (PTO-948) Paper No(s)/Mail Date. \_\_\_\_\_  
3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)  
Paper No(s)/Mail Date \_\_\_\_\_ 5) Notice of Informal Patent Application (PTO-152)  
6) Other: \_\_\_\_\_

## DETAILED ACTION

### ***Claim Rejections - 35 USC § 102***

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

2. Claims 15-16 and 18 are rejected under 35 U.S.C. 102(e) as being anticipated by Ono et al. (US 2003/0107129, previously cited, hereinafter, Ono.)

In regard to claim 15, in fig. 2, Ono discloses a method of fabricating bumps on a chip, the process comprising:

providing a chip 15 with an active surface (top surface) having a plurality of bonding pads 16 thereon and a backside (bottom side.)

forming at least a bump pad 14 on the backside of the chip; and

forming a bump 19 to the bump pad.

In regard to claim 16, Ono further discloses forming a metallic layer 14 or 21 on the backside of the chip; and

patterning the metallic layer to form the bump pad (figs. 11c and 11d show this step.)

In regard to claim 18, Ono further shows forming the protective element 18 on the active surface of the chip.

***Claim Rejections - 35 USC § 103***

3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

4. Claims 17 and 19 are rejected under 35 U.S.C. 103(a) as being unpatentable over Ono as applied to claims 15-16 above, and further in view of Akram (US 6,861,763, previously cited.)

In regard to claims 17 and 19, Ono discloses all of the claimed limitations as mentioned above except the mask has at least an opening so that the backside of the chip is exposed.

Akram, in fig. 6A, discloses an analogous package includes chip 12 pad 14, mask 30C wherein mask layer, or passivation layer, has an opening so the chip is exposed and forming a metallic layer 14 over the mask and the exposed portion of the chip. This opening further provides access to the to the chip for electrical connections. The mask or passivation layer then further removed to form a solder ball therein.

Therefore, it would have been obvious to one of ordinary skill in the art at the time of the invention was made to recognize opening portions on the chip in order to provide electrical connections.

5. Claim 20 is rejected under 35 U.S.C. 103(a) as being unpatentable over Ono as applied to claims 15-16 above, and further in view of Koh (US 2004/0135266, previously cited.)

In regard to claim 20, Ono discloses all of the claimed limitations as mentioned above, except using a wire-bonding machine in the process of making the electrical connection elements, bond pad, for example. It should be noted that wire bonding is widely used in the semiconductor package to form wire connections, bonding pad, and solder balls since it is widely available and provides easy access to such small area on the chip.

Therefore, it would have been obvious to one of ordinary skill in the art at the time of the invention was made to recognize the method as taught by Koh in order to facilitate the method of forming electrical connection elements.

#### ***Response to Arguments***

6. Applicant's arguments filed 8/2/05 have been fully considered but they are not persuasive. In response to applicant's argument that the references fail to show certain features of applicant's invention, it is noted that the features upon which applicant relies (i.e., mounted directly) are not recited in the rejected claim(s). Although the claims are interpreted in light of the specification, limitations from the specification are not read into the claims. See *In re Van Geuns*, 988 F.2d 1181, 26 USPQ2d 1057 (Fed. Cir. 1993).

Applicant further submits that the cited art, Ono, fails to disclose at least a bump pad on the backside of the chip and forming the bump on the bump pad. These

limitations indeed can be found in Ono's fig. 2, wherein the bump pad 14 is formed on the backside of the chip and the bump 19 is electrically formed on the pad.

### ***Conclusion***

7. **THIS ACTION IS MADE FINAL.** Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Nathan W. Ha whose telephone number is (571) 272-1707. The examiner can normally be reached on M-TH 8:00-7:00(EST).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Wael Fahmy can be reached on (571) 272-1705. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Nathan Ha  
October 3, 2005



HOAI PHAM  
PRIMARY EXAMINER